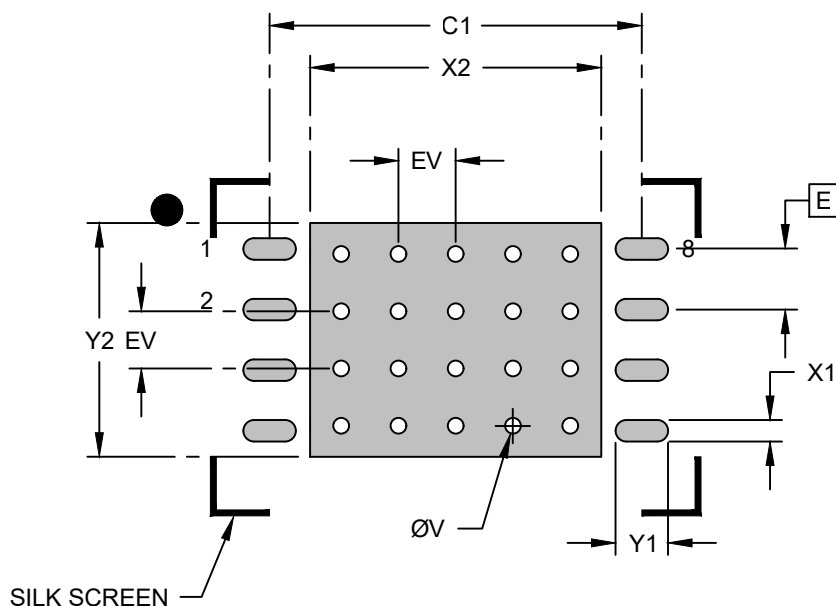


8-Lead Very, Very Thin Small Outline No-Lead (MN) - 8x6x0.8 mm Body [WSON] (Also Called WDFN)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packageing>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Optional Center Pad Width	X2			6.10
Optional Center Pad Length	Y2			4.90
Contact Pad Spacing	C1		7.80	
Contact Pad Width (X8)	X1			0.45
Contact Pad Length (X8)	Y1			0.95
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. The theoretically exact value is shown without tolerances.

2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during the reflow process.